

LM4050-N/LM4050-N-Q1 Precision Micropower Shunt Voltage Reference

Features

- Small Package: SOT-23
- No Output Capacitor Required
- **Tolerates Capacitive Loads**
- Fixed Reverse Breakdown Voltages of 2.048V, 2.500V, 4.096V, 5.000V, 8.192V, and 10.000V

Key Specifications (LM4050-N)

- Output Voltage Tolerance (A grade, 25°C) ±0.1% (maximum)
- Low Output Noise (10 Hz to 10 kHz) 41 μVrms (typical)
- Wide Operating Current Range 60 µA to 15
- Industrial Temperature Range -40°C to +85°C
- Extended Temperature Range -40°C to +125°C
- Low Temperature Coefficient 50 ppm/°C (maximum)
- LM4050-N-Q1 is AECQ100 Grade 1 Qualified and are Manufactured on an Automotive Grade Flow

2 Applications

- Portable, Battery-Powered Equipment
- **Data Acquisition Systems**
- Instrumentation
- **Process Control**
- **Energy Management**
- **Product Testing**
- Automotive
- **Precision Audio Components**

3 Description

Ideal for space critical applications, the LM4050-N precision voltage reference is available in the subminiature (3 mm x 1.3 mm) SOT-23 surface-mount package. The LM4050-N design eliminates the need for an external stabilizing capacitor while ensuring stability with any capacitive load, thus making the LM4050-N easy to use. Further reducing design effort is the availability of several fixed reverse breakdown voltages: 2.048V, 2.500V, 4.096V, 5.000V, 8.192V, and 10.000V. The minimum operating current increases from 60 µA for the LM4050-N-2.0 to 100 µA for the LM4050-N-10.0. All versions have a maximum operating current of 15 mA.

The LM4050-N utilizes fuse and zener-zap reverse breakdown voltage trim during wafer sort to ensure that the prime parts have an accuracy of better than ±0.1% (A grade) at 25°C. Bandgap reference temperature drift curvature correction and low dvnamic impedance ensure stable reverse breakdown voltage accuracy over a wide range of operating temperatures and currents.

All grades and voltage options of the LM4050-N are available in both an industrial temperature range (-40°C and +85°C) and an extended temperature range (-40°C and +125°C).

Device Information⁽¹⁾

PART NUMBER	PACKAGE	BODY SIZE (NOM)
LM4050-N	SOT-23	3 mm x 1.3 mm

(1) For all available packages, see the orderable addendum at the end of the data sheet.



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4 Revision History

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

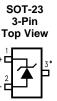
Changes from Revision E (April 2013) to Revision F	Page
 Deleted "-25" from (LM4050-N) in Key Specifications title and "A/-Q1B/-Q1C" from Key Specifications 	cation re: auto grade 1
Added Maximum Junction Temperature to Abs Max Ratings table	3
Added table notes to Operating Ratings table to clarify operating and high junction temperature	e ranges 3
Deleted "-N" from part numbers in EC table "Limits" column headers	4
Changes from Revision D (April 2013) to Revision E	Page
Changed layout of National Data Sheet to TI format	16

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Pin Configuration and Functions



*This pin must be left floating or connected to pin 2.

Specifications

6.1 Absolute Maximum Ratings (1)(2)

		20 mA
		10 mA
25°C) ⁽³⁾	DBZ Package	280 mW
DDZ Dookogo	Vapor phase (60 seconds)	+215°C
DBZ Package	Infrared (15 seconds)	+220°C
		150°C
		-65°C to +150°C
emperature DBZ Package Im Junction rature (4) E Temperature Usceptibility	Human Body Model ⁽⁵⁾	2 kV
	Machine Model ⁽⁵⁾	200V
		DBZ Package Vapor phase (60 seconds) Infrared (15 seconds) Human Body Model ⁽⁵⁾

- Absolute Maximum Ratings indicate limits beyond which damage to the device may occur. Operating Ratings indicate conditions for which the device is functional, but do not ensure specific performance limits. For ensured specifications and test conditions, see the Electrical Characteristics. The ensured specifications apply only for the test conditions listed. Some performance characteristics may degrade when the device is not operated under the listed test conditions.
- (2) If Military/Aerospace specified devices are required, please contact the Texas Instruments Sales Office/ Distributors for availability and specifications.
- The maximum power dissipation must be derated at elevated temperatures and is dictated by T_{Jmax} (maximum junction temperature), θ_{JA} (junction to ambient thermal resistance), and T_A (ambient temperature). The maximum allowable power dissipation at any temperature is $PD_{max} = (T_{Jmax} - T_A)/\theta_{JA}$ or the number given in the Absolute Maximum Ratings, whichever is lower. For the LM4050-N, $T_{Jmax} = 150$ °C, and the typical thermal resistance (θ_{JA}), when board mounted, is 326°C/W for the SOT-23 package.
- High junction temperatures degrade operating lifetimes. Operating lifetime is de-rated for junction temperatures greater than 125°C.
- The human body model is a 100 pF capacitor discharged through a 1.5 kΩ resistor into each pin. The machine model is a 200 pF capacitor discharged directly into each pin.

6.2 Operating Ratings⁽¹⁾, ⁽²⁾

Temperature Range		$(T_{min} \le T_A \le T_{max})$			
Industrial Temperature Range (3)		-40°C ≤ T _A ≤ +85°C			
Extended Temperature Range (3), (4)		-40°C ≤ T _A ≤ +125°C			
tondou romporataro riango ,	LM4050-N-2.0,	60 μA to 15 mA			
	LM4050-N-2.5	60 μA to 15 mA			
Payarea Current	LM4050-N-4.1	68 μA to 15 mA			
Reverse Current	LM4050-N-5.0	74 μA to 15 mA			
	LM4050-N-8.2	91 μA to 15 mA			
	LM4050-N-10.0	100 μA to 15 mA			

- (1) The maximum power dissipation must be derated at elevated temperatures and is dictated by T_{Jmax} (maximum junction temperature), θ_{JA} (junction to ambient thermal resistance), and T_A (ambient temperature). The maximum allowable power dissipation at any temperature is $PD_{max} = (T_{Jmax} - T_A)/\theta_{JA}$ or the number given in the Absolute Maximum Ratings, whichever is lower. For the LM4050-N, $T_{Jmax} = 150^{\circ}C$, and the typical thermal resistance (θ_{JA}) , when board mounted, is 326°C/W for the SOT-23 package.
- Operating ratings are conditions under the device is intended to be functional. For specifications and conditions, see Electrical Characteristics section.
- High junction temperatures degrade operating lifetimes. Operating lifetime is de-rated for junction temperatures greater than 125°C.
- Highest operating junction temperature for extended temperature range T₁ = 150°C.

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6.3 Electrical Characteristics - LM4050-N-2.0

Boldface limits apply for $T_A = T_J = T_{MIN}$ to T_{MAX} ; all other limits $T_A = T_J = 25$ °C. The grades A, B and C designate initial Reverse Breakdown Voltage tolerances of $\pm 0.1\%$, $\pm 0.2\%$, and 0.5% respectively.

PARAMETER		TEST CONDITIONS	TYP ⁽¹⁾	LM4050AIM3 LM4050AEM3 Limits ⁽²⁾	LM4050BIM3 LM4050BEM3 Limits ⁽²⁾	LM4050CIM3 LM4050CEM3 Limits ⁽²⁾	UNIT
V _R	Reverse Breakdown Voltage	I _R = 100 μA	2.048				V
	Reverse Breakdown Voltage	I _R = 100 μA		±2.048	±4.096	±10.24	mV (max)
	Tolerance ⁽³⁾	Industrial Temp. Range		±9.0112	±11.4688	±14.7456	mV (max)
		Extended Temp. Range		±12.288	±14.7456	±17.2032	mV (max)
I _{RMIN}	Minimum Operating Current		41				μA
				60	60	60	μA (max)
				65	65	65	μA (max)
$\Delta V_R/\Delta T$	Average Reverse Breakdown	I _R = 10 mA	±20				ppm/°C
	Voltage Temperature Coefficient ⁽³⁾	I _R = 1 mA	±15				ppm/°C
	Coomoon	I _R = 100 μA	±15	±50	±50	±50	ppm/°C (max)
$\Delta V_R/\Delta I_R$		I _{RMIN} ≤ I _R ≤ 1 mA	0.3				mV
	Change with Operating Current Change (4)			0.8	0.8	0.8	mV (max)
	- Change			1.2	1.2	1.2	mV (max)
		1 mA ≤ I _R ≤ 15 mA	2.3				mV
				6.0	6.0	6.0	mV (max)
				8.0	8.0	8.0	mV (max)
Z_R	Reverse Dynamic Impedance	I _R = 1 mA, f = 120 Hz, I _{AC} = 0.1 I _R	0.3				Ω
e _N	Wideband Noise	I _R = 100 μA 10 Hz ≤ f ≤ 10 kHz	34				μV_{rms}
ΔV_R	Reverse Breakdown Voltage Long Term Stability	t = 1000 hrs T = 25°C ±0.1°C I _R = 100 μA	120				ppm
V _{HYST}	Thermal Hysteresis	$\Delta T = -40$ °C to 125°C	0.7				mV

- (1) Typicals are at $T_J = 25$ °C and represent most likely parametric norm.
- (2) Limits are 100% production tested at 25°C. Limits over temperature are ensured through correlation using Statistical Quality Control (SQC) methods. The limits are used to calculate National's AOQL.
- (3) The boldface (over-temperature) limit for Reverse Breakdown Voltage Tolerance is defined as the room temperature Reverse Breakdown Voltage Tolerance $\pm [(\Delta V_R/\Delta T)(max\Delta T)(V_R)]$. Where, $\Delta V_R/\Delta T$ is the V_R temperature coefficient, $max\Delta T$ is the maximum difference in temperature from the reference point of 25°C to T_{MIN} or T_{MAX} , and V_R is the reverse breakdown voltage. The total over-temperature tolerance for the different grades in the industrial temperature range where $max\Delta T = 65^{\circ}C$ is shown below: A-grade: $\pm 0.425\% = \pm 0.1\% \pm 50$ ppm/°C × 65°C B-grade: $\pm 0.525\% = \pm 0.2\% \pm 50$ ppm/°C × 65°C C-grade: $\pm 0.825\% = \pm 0.5\% \pm 50$ ppm/°C × 65°C. Therefore, as an example, the A-grade LM4050-N-2.5 has an over-temperature Reverse Breakdown Voltage tolerance of $\pm 2.5V \times 0.425\% = \pm 11$ mV.
- (4) Load regulation is measured on pulse basis from no load to the specified load current. Output changes due to die temperature change must be taken into account separately.
- (5) Thermal hysteresis is defined as the difference in voltage measured at +25°C after cycling to temperature -40°C and the 25°C measurement after cycling to temperature +125°C.

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6.4 Electrical Characteristics - LM4050-N-2.5

Boldface limits apply for T_A = T_J = T_{MIN} to T_{MAX}; all other limits $T_A = T_J = 25$ °C. The grades A, B and C designate initial Reverse Breakdown Voltage tolerances of $\pm 0.1\%$, $\pm 0.2\%$, and 0.5% respectively.

PARAMETER		TEST CONDITIONS	TYP ⁽¹⁾	LM4050AIM3 LM4050AEM3 Limits ⁽²⁾	LM4050BIM3 LM4050BEM3 Limits ⁽²⁾	LM4050CIM3 LM4050CEM3 Limits ⁽²⁾	UNIT
V _R	Reverse Breakdown Voltage	I _R = 100 μA	2.500				V
	Reverse Breakdown Voltage	I _R = 100 μA		±2.5	±5.0	±13	mV (max)
	Tolerance ⁽³⁾	Industrial Temp. Range		±11	±14	±21	mV (max)
		Extended Temp. Range		±15	±18	±25	mV (max)
I _{RMIN}	Minimum Operating Current		41				μA
				60	60	60	μA (max)
				65	65	65	μA (max)
$\Delta V_R/\Delta T$	Average Reverse Breakdown	I _R = 10 mA	±20				ppm/°C
	Voltage Temperature Coefficient ⁽³⁾	I _R = 1 mA	±15				ppm/°C
		I _R = 100 μA	±15	±50	±50	±50	ppm/°C (max)
$\Delta V_R / \Delta I_R$	Reverse Breakdown Voltage	I _{RMIN} ≤ I _R ≤ 1 mA	0.3				mV
	Change with Operating Current Change (4)			0.8	0.8	0.8	mV (max)
	Gridings			1.2	1.2	1.2	mV (max)
		1 mA ≤ I _R ≤ 15 mA	2.3				mV
				6.0	6.0	6.0	mV (max)
				8.0	8.0	8.0	mV (max)
Z_R	Reverse Dynamic Impedance	I _R = 1 mA, f = 120 Hz, I _{AC} = 0.1 I _R	0.3				Ω
e _N	Wideband Noise	I _R = 100 μA 10 Hz ≤ f ≤ 10 kHz	41				μV _{rms}
ΔV_R	Reverse Breakdown Voltage Long Term Stability	t = 1000 hrs T = 25°C ±0.1°C I _R = 100 μA	120				ppm
V _{HYST}	Thermal Hysteresis	$\Delta T = -40$ °C to 125°C	0.7				mV

- (1) Typicals are at $T_J = 25$ °C and represent most likely parametric norm.
- (2) Limits are 100% production tested at 25°C. Limits over temperature are ensured through correlation using Statistical Quality Control (SQC) methods. The limits are used to calculate National's AOQL.
- (3) The boldface (over-temperature) limit for Reverse Breakdown Voltage Tolerance is defined as the room temperature Reverse Breakdown Voltage Tolerance $\pm [(\Delta V_R/\Delta T)(max\Delta T)(V_R)]$. Where, $\Delta V_R/\Delta T$ is the V_R temperature coefficient, $max\Delta T$ is the maximum difference in temperature from the reference point of 25°C to T_{MIN} or T_{MAX} , and V_R is the reverse breakdown voltage. The total over-temperature tolerance for the different grades in the industrial temperature range where $max\Delta T = 65^{\circ}C$ is shown below: A-grade: $\pm 0.425\% = \pm 0.1\% \pm 50$ ppm/°C × 65°C B-grade: $\pm 0.525\% = \pm 0.2\% \pm 50$ ppm/°C × 65°C C-grade: $\pm 0.825\% = \pm 0.5\% \pm 50$ ppm/°C × 65°C. Therefore, as an example, the A-grade LM4050-N-2.5 has an over-temperature Reverse Breakdown Voltage tolerance of $\pm 2.5V \times 0.425\% = \pm 11$ mV.
- (4) Load regulation is measured on pulse basis from no load to the specified load current. Output changes due to die temperature change must be taken into account separately.
- (5) Thermal hysteresis is defined as the difference in voltage measured at +25°C after cycling to temperature -40°C and the 25°C measurement after cycling to temperature +125°C.

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6.5 Electrical Characteristics - LM4050-N-4.1

Boldface limits apply for $T_A = T_J = T_{MIN}$ to T_{MAX} ; all other limits $T_A = T_J = 25$ °C. The grades A, B and C designate initial Reverse Breakdown Voltage tolerances of $\pm 0.1\%$, $\pm 0.2\%$, and 0.5% respectively.

	PARAMETER	TEST CONDITIONS	TYP ⁽¹⁾	LM4050AIM3 LM4050AEM3 Limits ⁽²⁾	LM4050BIM3 LM4050BEM3 Limits ⁽²⁾	LM4050CIM3 LM4050CEM3 Limits ⁽²⁾	UNIT
V_R	Reverse Breakdown Voltage	I _R = 100 μA	4.096				V
	Reverse Breakdown Voltage	I _R = 100 μA		±4.1	±8.2	±21	mV (max)
	Tolerance ⁽³⁾	Industrial Temp. Range		±18	±22	±34	mV (max)
		Extended Temp. Range		±25	±29	±41	mV (max)
I _{RMIN}	Minimum Operating Current		52				μA
				68	68	68	μA (max)
		Industrial Temp. Range		73	73	73	μA (max)
		Extended Temp. Range		78	78	78	μA (max)
$\Delta V_R/\Delta T$	Average Reverse Breakdown	I _R = 10 mA	±30				ppm/°C
	Voltage Temperature Coefficient ⁽³⁾	I _R = 1 mA	±20				ppm/°C
		Ι _R = 100 μΑ	±20	±50	±50	±50	ppm/°C (max)
$\Delta V_R/\Delta I_R$	Reverse Breakdown Voltage	$I_{RMIN} \le I_R \le 1 \text{ mA}$	0.2				mV
	Change with Operating Current Change (4)			0.9	0.9	0.9	mV (max)
	- Change			1.2	1.2	1.2	mV (max)
		1 mA ≤ I _R ≤ 15 mA	2.0				mV
				7.0	7.0	7.0	mV (max)
				10.0	10.0	10.0	mV (max)
Z _R	Reverse Dynamic Impedance	$I_R = 1 \text{ mA, f} = 120 \text{ Hz,}$ $I_{AC} = 0.1 I_R$	0.5				Ω
e _N	Wideband Noise	I _R = 100 μA 10 Hz ≤ f ≤ 10 kHz	93				μV_{rms}
ΔV_R	Reverse Breakdown Voltage Long Term Stability	t = 1000 hrs T = 25°C ±0.1°C I _R = 100 μA	120				ppm
V _{HYST}	Thermal Hysteresis (5)	$\Delta T = -40^{\circ}C$ to 125°C	1.148				mV

- (1) Typicals are at T_J = 25°C and represent most likely parametric norm.
- (2) Limits are 100% production tested at 25°C. Limits over temperature are ensured through correlation using Statistical Quality Control (SQC) methods. The limits are used to calculate National's AOQL.
- (3) The boldface (over-temperature) limit for Reverse Breakdown Voltage Tolerance is defined as the room temperature Reverse Breakdown Voltage Tolerance ±[(ΔV _R/ΔT)(maxΔT)(V_R)]. Where, ΔV_R/ΔT is the V_R temperature coefficient, maxΔT is the maximum difference in temperature from the reference point of 25°C to T _{MIN} or T_{MAX}, and V_R is the reverse breakdown voltage. The total over-temperature tolerance for the different grades in the industrial temperature range where maxΔT = 65°C is shown below: A-grade: ±0.425% = ±0.1% ±50 ppm/°C × 65°C B-grade: ±0.525% = ±0.2% ±50 ppm/°C × 65°C C-grade: ±0.825% = ±0.5% ±50 ppm/°C × 65°C. Therefore, as an example, the A-grade LM4050-N-2.5 has an over-temperature Reverse Breakdown Voltage tolerance of ±2.5V × 0.425% = ±11 mV.
- (4) Load regulation is measured on pulse basis from no load to the specified load current. Output changes due to die temperature change must be taken into account separately.
- (5) Thermal hysteresis is defined as the difference in voltage measured at +25°C after cycling to temperature -40°C and the 25°C measurement after cycling to temperature +125°C.

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6.6 Electrical Characteristics - LM4050-N-5.0

Boldface limits apply for T_A = T_J = T_{MIN} to T_{MAX}; all other limits $T_A = T_J = 25$ °C. The grades A, B and C designate initial Reverse Breakdown Voltage tolerances of $\pm 0.1\%$, $\pm 0.2\%$ and 0.5% respectively.

	PARAMETER	TEST CONDITIONS	TYP ⁽¹⁾	LM4050AIM3 LM4050AEM3 Limits ⁽²⁾	LM4050BIM3 LM4050BEM3 Limits ⁽²⁾	LM4050CIM3 LM4050CEM3 Limits ⁽²⁾	UNIT
V_R	Reverse Breakdown Voltage	I _R = 100 μA	5.000				V
	Reverse Breakdown Voltage	I _R = 100 μA		±5.0	±10	±25	mV (max)
	Tolerance ⁽³⁾	Industrial Temp. Range		±22	±27	±42	mV (max)
		Extended Temp. Range		±30	±35	±50	mV (max)
I _{RMIN}	Minimum Operating Current		56				μA
				74	74	74	μA (max)
		Industrial Temp. Range		80	80	80	μA (max)
		Extended Temp. Range		90	90	90	μA (max)
$\Delta V_R/\Delta T$	Average Reverse Breakdown	I _R = 10 mA	±30				ppm/°C
	Voltage Temperature Coefficient ⁽⁾	I _R = 1 mA	±20				ppm/°C
		Ι _R = 100 μΑ	±20	±50	±50	±50	ppm/°C (max)
$\Delta V_R/\Delta I_R$	Reverse Breakdown Voltage	$I_{RMIN} \le I_R \le 1 \text{ mA}$	0.2				mV
	Change with Operating Current Change (4)			1.0	1.0	1.0	mV (max)
	- Change			1.4	1.4	1.4	mV (max)
		1 mA ≤ I _R ≤ 15 mA	2.0				mV
				8.0	8.0	8.0	mV (max)
				12.0	12.0	12.0	mV (max)
Z _R	Reverse Dynamic Impedance	I _R = 1 mA, f = 120 Hz,	0.5				Ω
		I _{AC} = 0.1 I _R					Ω (max)
e _N	Wideband Noise	I _R = 100 μA 10 Hz ≤ f ≤ 10 kHz	93				μV_{rms}
ΔV_R	Reverse Breakdown Voltage Long Term Stability	t = 1000 hrs T = 25°C ±0.1°C I _R = 100 μA	120				ppm
V _{HYST}	Thermal Hysteresis ⁽⁵⁾	$\Delta T = -40$ °C to 125°C	1.4				mV

- (1) Typicals are at $T_J = 25^{\circ}C$ and represent most likely parametric norm.
- (2) Limits are 100% production tested at 25°C. Limits over temperature are ensured through correlation using Statistical Quality Control (SQC) methods. The limits are used to calculate National's AOQL.
- (3) The boldface (over-temperature) limit for Reverse Breakdown Voltage Tolerance is defined as the room temperature Reverse Breakdown Voltage Tolerance $\pm [(\Delta V_R/\Delta T)(max\Delta T)(V_R)]$. Where, $\Delta V_R/\Delta T$ is the V_R temperature coefficient, $max\Delta T$ is the maximum difference in temperature from the reference point of 25°C to T_{MIN} or T_{MAX} , and V_R is the reverse breakdown voltage. The total over-temperature tolerance for the different grades in the industrial temperature range where $max\Delta T = 65^{\circ}C$ is shown below: A-grade: $\pm 0.425\% = \pm 0.1\% \pm 50$ ppm/°C $\times 65^{\circ}C$ B-grade: $\pm 0.525\% = \pm 0.2\% \pm 50$ ppm/°C $\times 65^{\circ}C$ C-grade: $\pm 0.825\% = \pm 0.5\% \pm 50$ ppm/°C $\times 65^{\circ}C$. Therefore, as an example, the A-grade LM4050-N-2.5 has an over-temperature Reverse Breakdown Voltage tolerance of $\pm 2.5V \times 0.425\% = \pm 11$ mV.
- (4) Load regulation is measured on pulse basis from no load to the specified load current. Output changes due to die temperature change must be taken into account separately.
- (5) Thermal hysteresis is defined as the difference in voltage measured at +25°C after cycling to temperature -40°C and the 25°C measurement after cycling to temperature +125°C.

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6.7 Electrical Characteristics - LM4050-N-8.2

Boldface limits apply for $T_A = T_J = T_{MIN}$ to T_{MAX} ; all other limits $T_A = T_J = 25$ °C. The grades A, B and C designate initial Reverse Breakdown Voltage tolerances of $\pm 0.1\%$ and $\pm 0.2\%$ and 0.5% respectively.

PARAMETER		TEST CONDITION	TYP ⁽¹⁾	LM4050AIM3 LM4050AEM3 Limits ⁽²⁾	LM4050BIM3 LM4050BEM3 Limits ⁽²⁾	LM4050CIM3 LM4050CEM3 Limits ⁽²⁾	UNIT
V_R	Reverse Breakdown Voltage	I _R = 150 μA	8.192				V
	Reverse Breakdown Voltage	I _R = 150 μA		±8.2	±16	±41	mV (max)
	Tolerance (3)	Industrial Temp. Range		±35	±43	±68	mV (max)
		Extended Temp. Range		±49	±57	±82	mV (max)
I _{RMIN}	Minimum Operating Current		74				μA
				91	91	91	μA (max)
		Industrial Temp. Range		95	95	95	μA (max)
		Extended Temp. Range		100	100	100	μA (max)
$\Delta V_R/\Delta T$	Average Reverse Breakdown	I _R = 10 mA	±40				ppm/°C
	Voltage Temperature Coefficient (3)	I _R = 1 mA	±20				ppm/°C
		Ι _R = 150 μΑ	±20	±50	±50	±50	ppm/°C (max)
$\Delta V_R/\Delta I_R$	Reverse Breakdown Voltage	$I_{RMIN} \le I_R \le 1 \text{ mA}$	0.6				mV
	Change with Operating Current Change (4)			1.3	1.3	1.3	mV (max)
	onange			2.5	2.5	2.5	mV (max)
		1 mA ≤ I _R ≤ 15 mA	7.0				mV
				10.0	10.0	10.0	mV (max)
				18.0	18.0	18.0	mV (max)
Z _R	Reverse Dynamic Impedance	I _R = 1 mA, f = 120 Hz, I _{AC} = 0.1 I _R	0.6				Ω
e _N	Wideband Noise	I _R = 150 μA 10 Hz ≤ f ≤ 10 kHz	150				μV_{rms}
ΔV_R	Reverse Breakdown Voltage Long Term Stability	t = 1000 hrs T = 25°C ±0.1°C I _R = 150 μA	120				ppm
V _{HYST}	Thermal Hysteresis	$\Delta T = -40$ °C to 125°C	2.3				mV

- (1) Typicals are at $T_J = 25$ °C and represent most likely parametric norm.
- (2) Limits are 100% production tested at 25°C. Limits over temperature are ensured through correlation using Statistical Quality Control (SQC) methods. The limits are used to calculate National's AOQL.
- (3) The boldface (over-temperature) limit for Reverse Breakdown Voltage Tolerance is defined as the room temperature Reverse Breakdown Voltage Tolerance $\pm [(\Delta V_R/\Delta T)(max\Delta T)(V_R)]$. Where, $\Delta V_R/\Delta T$ is the V_R temperature coefficient, $max\Delta T$ is the maximum difference in temperature from the reference point of 25°C to T $_{MIN}$ or T $_{MAX}$, and V_R is the reverse breakdown voltage. The total over-temperature tolerance for the different grades in the industrial temperature range where $max\Delta T = 65^{\circ}C$ is shown below: A-grade: $\pm 0.425\% = \pm 0.1\% \pm 50$ ppm/°C $\times 65^{\circ}C$ B-grade: $\pm 0.525\% = \pm 0.2\% \pm 50$ ppm/°C $\times 65^{\circ}C$ C-grade: $\pm 0.825\% = \pm 0.5\% \pm 50$ ppm/°C $\times 65^{\circ}C$. Therefore, as an example, the A-grade LM4050-N-2.5 has an over-temperature Reverse Breakdown Voltage tolerance of $\pm 2.5V \times 0.425\% = \pm 11$ mV.
- (4) Load regulation is measured on pulse basis from no load to the specified load current. Output changes due to die temperature change must be taken into account separately.
- (5) Thermal hysteresis is defined as the difference in voltage measured at +25°C after cycling to temperature -40°C and the 25°C measurement after cycling to temperature +125°C.

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6.8 Electrical Characteristics - LM4050-N-10.0

Boldface limits apply for $T_A = T_J = T_{MIN}$ to T_{MAX} ; all other limits $T_A = T_J = 25$ °C. The grades A, B and C designate initial Reverse Breakdown Voltage tolerances of ±0.1% and ±0.2% and 0.5% respectively.

	PARAMETER	TEST CONDITION	TYP	LM4050AIM3 LM4050AEM3 Limits	LM4050BIM3 LM4050BEM3 Limits	LM4050CIM3 LM4050CEM3 Limits	UNIT
V _R	Reverse Breakdown Voltage	I _R = 150 μA	10.00				V
	Reverse Breakdown Voltage Tolerance ⁽³⁾	I _R = 150 μA		±10	±20	±50	mV (max)
		Industrial Temp. Range		±43	±53	±83	mV (max)
		Extended Temp. Range		±60	±70	±100	mV (max)
I _{RMIN}	Minimum Operating Current		80				μΑ
				100	100	100	μA (max)
		Industrial Temp. Range		103	103	103	μA (max)
		Extended Temp. Range		110	110	110	μA (max)
$\Delta V_R/\Delta T$	Average Reverse Breakdown	I _R = 10 mA	±40				ppm/°C
	Voltage Temperature Coefficient (3)	I _R = 1 mA	±20				ppm/°C
		Ι _R = 150 μΑ	±20	±50	±50	±50	ppm/°C (max)
$\Delta V_R / \Delta I_R$	Reverse Breakdown Voltage	I _{RMIN} ≤ I _R ≤ 1 mA	0.8				mV
	Change with Operating Current Change ⁽⁴⁾			1.5	1.5	1.5	mV (max)
				3.5	3.5	3.5	mV (max)
		1 mA ≤ I _R ≤ 15 mA	8.0				mV
				12.0	12.0	12.0	mV (max)
				23.0	23.0	23.0	mV (max)
Z _R	Reverse Dynamic Impedance	I _R = 1 mA, f = 120 Hz, I _{AC} = 0.1 I _R	0.7				Ω
e _N	Wideband Noise	I _R = 150 μA 10 Hz ≤ f ≤ 10 kHz	150				μV_{rms}
ΔV_R	Reverse Breakdown Voltage Long Term Stability	t = 1000 hrs T = 25°C ±0.1°C I _R = 150 μA	120				ppm
V_{HYST}	Thermal Hysteresis	$\Delta T = -40$ °C to 125°C	2.8				mV

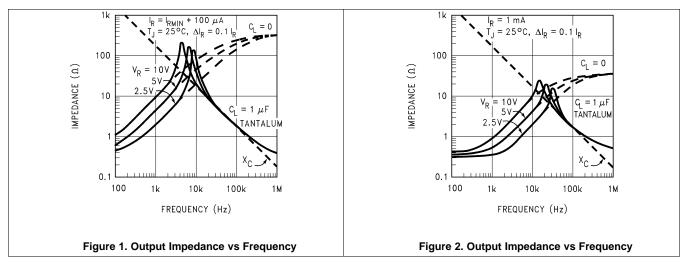
- (1) Typicals are at $T_J = 25^{\circ}$ C and represent most likely parametric norm.
- Limits are 100% production tested at 25°C. Limits over temperature are ensured through correlation using Statistical Quality Control (SQC) methods. The limits are used to calculate National's AOQL.
- The boldface (over-temperature) limit for Reverse Breakdown Voltage Tolerance is defined as the room temperature Reverse Breakdown Voltage Tolerance $\pm [(\Delta V_R/\Delta T)(max\Delta T)(V_R)]$. Where, $\Delta V_R/\Delta T$ is the V_R temperature coefficient, $max\Delta T$ is the maximum difference in temperature from the reference point of 25°C to T_{MIN} or T_{MAX} , and V_R is the reverse breakdown voltage. The total overtemperature tolerance for the different grades in the industrial temperature range where max $\Delta T = 65$ °C is shown below: $\pm 0.425\% = \pm 0.1\% \pm 50 \text{ ppm/°C} \times 65°C$ B-grade: $\pm 0.525\% = \pm 0.2\% \pm 50 \text{ ppm/°C} \times 65°C$ C-grade: $\pm 0.825\% = \pm 0.5\% \pm 50 \text{ ppm/°C} \times$ 65°C. Therefore, as an example, the A-grade LM4050-N-2.5 has an over-temperature Reverse Breakdown Voltage tolerance of ±2.5V x $0.425\% = \pm 11 \text{ mV}.$
- (4) Load regulation is measured on pulse basis from no load to the specified load current. Output changes due to die temperature change must be taken into account separately.

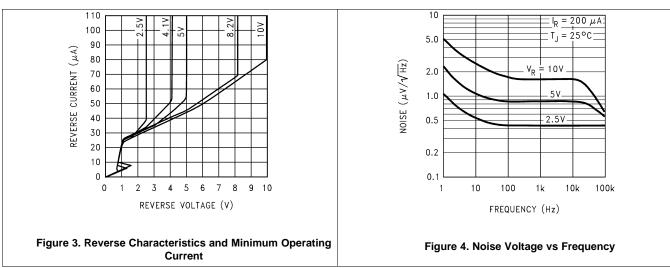
Product Folder Links: LM4050-N LM4050-N-Q1

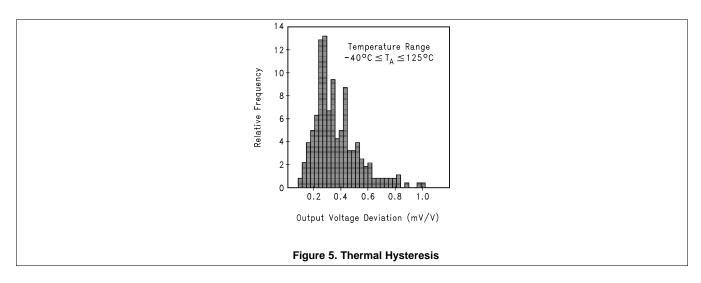
Thermal hysteresis is defined as the difference in voltage measured at +25°C after cycling to temperature -40°C and the 25°C measurement after cycling to temperature +125°C.



6.9 Typical Performance Characteristics





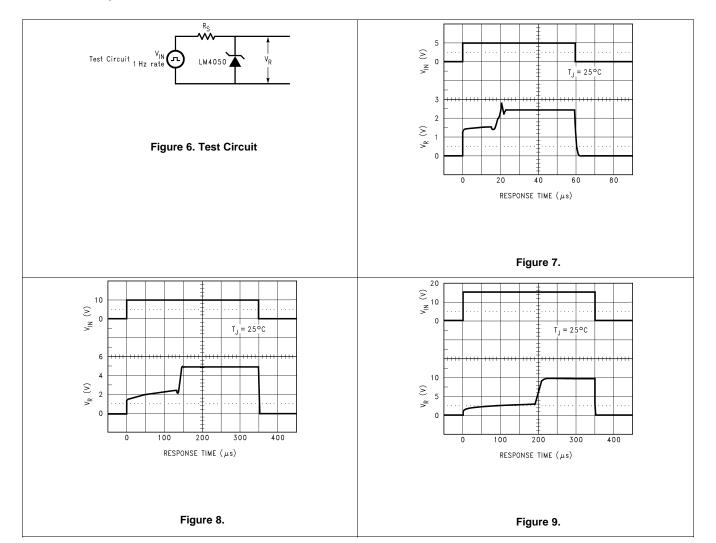


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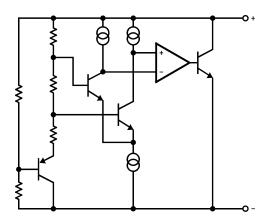
6.9.1 Start-Up Characteristics





7 Detailed Description

7.1 Functional Block Diagram





8 Application and Implementation

NOTE

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes. Customers should validate and test their design implementation to confirm system functionality.

8.1 Applications Information

The LM4050-N is a precision micro-power curvature-corrected bandgap shunt voltage reference. For space critical applications, the LM4050-N is available in the sub-miniature SOT-23 surface-mount package. The LM4050-N has been designed for stable operation without the need of an external capacitor connected between the "+" pin and the "-" pin. If, however, a bypass capacitor is used, the LM4050-N remains stable. Reducing design effort is the availability of several fixed reverse breakdown voltages: 2.048V, 2.500V, 4.096V, 5.000V, 8.192V, and 10.000V. The minimum operating current increases from 60 μ A for the LM4050-N-2.0 to 100 μ A for the LM4050-N-10.0. All versions have a maximum operating current of 15 mA.

LM4050-Ns in the SOT-23 packages have a parasitic Schottky diode between pin 2 (–) and pin 3 (Die attach interface contact). Therefore, pin 3 of the SOT-23 package must be left floating or connected to pin 2.

The 4.096V version allows single +5V 12-bit ADCs or DACs to operate with an LSB equal to 1 mV. For 12-bit ADCs or DACs that operate on supplies of 10V or greater, the 8.192V version gives 2 mV per LSB.

The typical thermal hysteresis specification is defined as the change in +25°C voltage measured after thermal cycling. The device is thermal cycled to temperature -40°C and then measured at 25°C. Next the device is thermal cycled to temperature +125°C and again measured at 25°C. The resulting V_{OUT} delta shift between the 25°C measurements is thermal hysteresis. Thermal hysteresis is common in precision references and is induced by thermal-mechanical package stress. Changes in environmental storage temperature, operating temperature and board mounting temperature are all factors that can contribute to thermal hysteresis.

In a conventional shunt regulator application (Figure 10) , an external series resistor ($R_{\rm S}$) is connected between the supply voltage and the LM4050-N. $R_{\rm S}$ determines the current that flows through the load ($I_{\rm L}$) and the LM4050-N ($I_{\rm Q}$). Since load current and supply voltage may vary, $R_{\rm S}$ should be small enough to supply at least the maximum ensured $I_{\rm RMIN}$ (spec. table) to the LM4050-N even when the supply voltage is at its minimum and the load current is at its maximum value. When the supply voltage is at its maximum and $I_{\rm L}$ is at its minimum, $R_{\rm S}$ should be large enough so that the current flowing through the LM4050-N is less than 15 mA.

 R_S is determined by the supply voltage, (V_S) , the load and operating current, $(I_L$ and $I_Q)$, and the LM4050-N's reverse breakdown voltage, V_R .

$$\mathsf{R}_{\mathsf{S}} = \frac{\mathsf{V}_{\mathsf{S}} - \mathsf{V}_{\mathsf{R}}}{\mathsf{I}_{\mathsf{L}} + \mathsf{I}_{\mathsf{Q}}} \tag{1}$$

8.2 Typical Applications

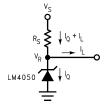
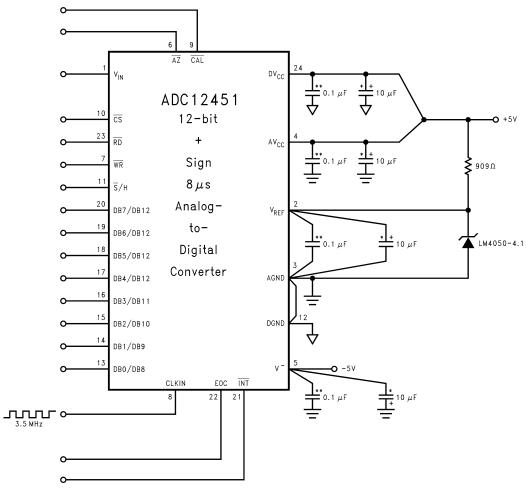


Figure 10. Shunt Regulator



Typical Applications (continued)



^{**}Ceramic monolithic

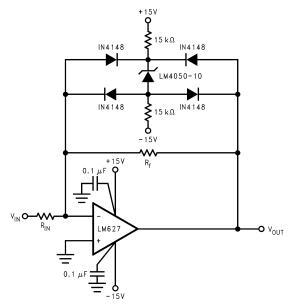
Figure 11. LM4050-N-4.1'S Nominal 4.096 Breakdown Voltage gives ADC12451 1 MV/LSB

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^{*}Tantalum

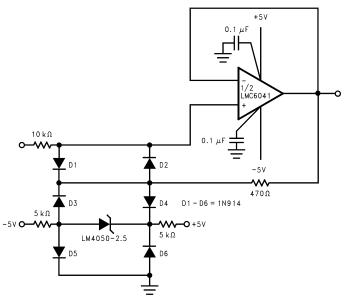


Typical Applications (continued)



Bounded amplifier reduces saturation-induced delays and can prevent succeeding stage damage. Nominal clamping voltage is $\pm 11.5V$ (LM4050-N's reverse breakdown voltage +2 diode V_F).

Figure 12. Bounded Amplifier



The bounding voltage is ±4V with the LM4050-N-2.5 (LM4050-N's reverse breakdown voltage + 3 diode V_F).

Figure 13. Protecting Op Amp Input

Product Folder Links: LM4050-N LM4050-N-Q1

Typical Applications (continued)

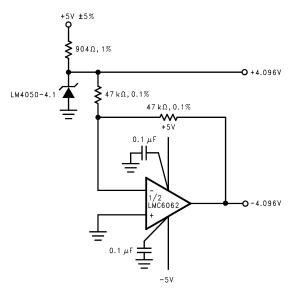
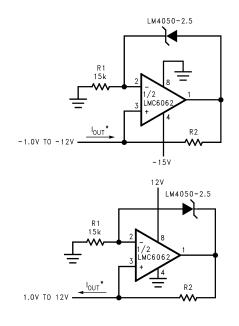


Figure 14. Precision ±4.096v Reference



 $*I_{OUT} - \frac{2.5V}{R2}$

Figure 15. Precision 1 MA To 1 mA Current Sources

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PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead/Ball Finish (6)	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
LM4050AEM3-10/NOPB	ACTIVE	SOT-23	DBZ	3	1000	Green (RoHS & no Sb/Br)	CUSN	Level-1-260C-UNLIM	-40 to 125	RGA	Samples
LM4050AEM3-2.0	NRND	SOT-23	DBZ	3		TBD	Call TI	Call TI	-40 to 125	RNA	
LM4050AEM3-2.0/NOPB	ACTIVE	SOT-23	DBZ	3	1000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 125	RNA	Samples
LM4050AEM3-2.5	NRND	SOT-23	DBZ	3	1000	TBD	Call TI	Call TI	-40 to 125	RCA	
LM4050AEM3-2.5/NOPB	ACTIVE	SOT-23	DBZ	3	1000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 125	RCA	Samples
LM4050AEM3-5.0	NRND	SOT-23	DBZ	3	1000	TBD	Call TI	Call TI	-40 to 125	REA	
LM4050AEM3-5.0/NOPB	ACTIVE	SOT-23	DBZ	3	1000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 125	REA	Samples
LM4050AEM3-8.2	NRND	SOT-23	DBZ	3	1000	TBD	Call TI	Call TI	-40 to 125	RFA	
LM4050AEM3-8.2/NOPB	ACTIVE	SOT-23	DBZ	3	1000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 125	RFA	Samples
LM4050AEM3X-10	NRND	SOT-23	DBZ	3		TBD	Call TI	Call TI	-40 to 125	RGA	
LM4050AEM3X-10/NOPB	ACTIVE	SOT-23	DBZ	3	3000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 125	RGA	Samples
LM4050AEM3X-2.5/NOPB	ACTIVE	SOT-23	DBZ	3	3000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 125	RCA	Samples
LM4050AEM3X-5.0/NOPB	ACTIVE	SOT-23	DBZ	3	3000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 125	REA	Samples
LM4050AIM3-10	NRND	SOT-23	DBZ	3	1000	TBD	Call TI	Call TI	-40 to 85	RGA	
LM4050AIM3-10/NOPB	ACTIVE	SOT-23	DBZ	3	1000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 85	RGA	Samples
LM4050AIM3-2.5	NRND	SOT-23	DBZ	3	1000	TBD	Call TI	Call TI	-40 to 85	RCA	
LM4050AIM3-2.5/NOPB	ACTIVE	SOT-23	DBZ	3	1000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 85	RCA	Samples
LM4050AIM3-4.1	NRND	SOT-23	DBZ	3	1000	TBD	Call TI	Call TI	-40 to 85	RDA	
LM4050AIM3-4.1/NOPB	ACTIVE	SOT-23	DBZ	3	1000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 85	RDA	Samples
LM4050AIM3-5.0	NRND	SOT-23	DBZ	3	1000	TBD	Call TI	Call TI	-40 to 85	REA	
LM4050AIM3-5.0/NOPB	ACTIVE	SOT-23	DBZ	3	1000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 85	REA	Samples



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Orderable Device	Status	Package Type	Package	Pins	Package	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking	Samples
	(1)		Drawing		Qty	(2)	(6)	(3)		(4/5)	
LM4050AIM3X-2.5/NOPB	ACTIVE	SOT-23	DBZ	3	3000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 85	RCA	Samples
LM4050AIM3X-4.1/NOPB	ACTIVE	SOT-23	DBZ	3	3000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 85	RDA	Samples
LM4050AIM3X-5.0	NRND	SOT-23	DBZ	3	3000	TBD	Call TI	Call TI	-40 to 85	REA	
LM4050AIM3X-5.0/NOPB	ACTIVE	SOT-23	DBZ	3	3000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 85	REA	Samples
LM4050BEM3-10/NOPB	ACTIVE	SOT-23	DBZ	3	1000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 125	RGB	Samples
LM4050BEM3-2.5	NRND	SOT-23	DBZ	3	1000	TBD	Call TI	Call TI	-40 to 125	RCB	
LM4050BEM3-2.5/NOPB	ACTIVE	SOT-23	DBZ	3	1000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 125	RCB	Samples
LM4050BEM3-4.1/NOPB	ACTIVE	SOT-23	DBZ	3	1000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 125	RDB	Samples
LM4050BEM3-5.0	NRND	SOT-23	DBZ	3	1000	TBD	Call TI	Call TI	-40 to 125	REB	
LM4050BEM3-5.0/NOPB	ACTIVE	SOT-23	DBZ	3	1000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 125	REB	Samples
LM4050BEM3-8.2/NOPB	ACTIVE	SOT-23	DBZ	3	1000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 125	RFB	Samples
LM4050BEM3X-10/NOPB	ACTIVE	SOT-23	DBZ	3	3000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 125	RGB	Samples
LM4050BEM3X-2.5/NOPB	ACTIVE	SOT-23	DBZ	3	3000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 125	RCB	Samples
LM4050BEM3X-5.0/NOPB	ACTIVE	SOT-23	DBZ	3	3000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 125	REB	Samples
LM4050BIM3-10/NOPB	ACTIVE	SOT-23	DBZ	3	1000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 85	RGB	Samples
LM4050BIM3-2.5	NRND	SOT-23	DBZ	3	1000	TBD	Call TI	Call TI	-40 to 85	RCB	
LM4050BIM3-2.5/NOPB	ACTIVE	SOT-23	DBZ	3	1000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 85	RCB	Samples
LM4050BIM3-4.1/NOPB	ACTIVE	SOT-23	DBZ	3	1000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 85	RDB	Samples
LM4050BIM3-5.0	NRND	SOT-23	DBZ	3	1000	TBD	Call TI	Call TI	-40 to 85	REB	
LM4050BIM3-5.0/NOPB	ACTIVE	SOT-23	DBZ	3	1000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 85	REB	Samples





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Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
LM4050BIM3X-2.0/NOPB	ACTIVE	SOT-23	DBZ	3	3000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 85	RNB	Samples
LM4050BIM3X-2.5/NOPB	ACTIVE	SOT-23	DBZ	3	3000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 85	RCB	Samples
LM4050BIM3X-4.1/NOPB	ACTIVE	SOT-23	DBZ	3	3000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 85	RDB	Samples
LM4050BIM3X-5.0/NOPB	ACTIVE	SOT-23	DBZ	3	3000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 85	REB	Samples
LM4050CEM3-10/NOPB	ACTIVE	SOT-23	DBZ	3	1000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM		RGC	Samples
LM4050CEM3-2.5	NRND	SOT-23	DBZ	3	1000	TBD	Call TI	Call TI	-40 to 125	RCC	
LM4050CEM3-2.5/NOPB	ACTIVE	SOT-23	DBZ	3	1000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 125	RCC	Sample
LM4050CEM3-5.0	NRND	SOT-23	DBZ	3	1000	TBD	Call TI	Call TI		REC	
LM4050CEM3-5.0/NOPB	ACTIVE	SOT-23	DBZ	3	1000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM		REC	Sample
LM4050CEM3X-2.5/NOPB	ACTIVE	SOT-23	DBZ	3	3000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 125	RCC	Sample
LM4050CEM3X-5.0/NOPB	ACTIVE	SOT-23	DBZ	3	3000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM		REC	Sample
LM4050CIM3-10/NOPB	ACTIVE	SOT-23	DBZ	3	1000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 85	RGC	Sample
LM4050CIM3-2.5	NRND	SOT-23	DBZ	3	1000	TBD	Call TI	Call TI	-40 to 85	RCC	
LM4050CIM3-2.5/NOPB	ACTIVE	SOT-23	DBZ	3	1000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 85	RCC	Sample
LM4050CIM3-4.1	NRND	SOT-23	DBZ	3	1000	TBD	Call TI	Call TI	-40 to 85	RDC	
LM4050CIM3-4.1/NOPB	ACTIVE	SOT-23	DBZ	3	1000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 85	RDC	Sample
LM4050CIM3-5.0	NRND	SOT-23	DBZ	3	1000	TBD	Call TI	Call TI	-40 to 85	REC	
LM4050CIM3-5.0/NOPB	ACTIVE	SOT-23	DBZ	3	1000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 85	REC	Sample
LM4050CIM3X-2.0/NOPB	ACTIVE	SOT-23	DBZ	3	3000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 85	RNC	Sample
LM4050CIM3X-2.5/NOPB	ACTIVE	SOT-23	DBZ	3	3000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 85	RCC	Sample



Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Sample
LM4050CIM3X-4.1/NOPB	ACTIVE	SOT-23	DBZ	3	3000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 85	RDC	Sample
LM4050CIM3X-5.0/NOPB	ACTIVE	SOT-23	DBZ	3	3000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 85	REC	Sample
LM4050QAEM3-10/NOPB	ACTIVE	SOT-23	DBZ	3	1000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 125	RYA	Sample
LM4050QAEM3-2.0/NOPB	ACTIVE	SOT-23	DBZ	3	1000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 125	RSA	Sample
LM4050QAEM3-2.5/NOPB	ACTIVE	SOT-23	DBZ	3	1000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 125	RTA	Sample
LM4050QAEM3-4.1/NOPB	ACTIVE	SOT-23	DBZ	3	1000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 125	RUA	Sample
LM4050QAEM3-5.0/NOPB	ACTIVE	SOT-23	DBZ	3	1000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 125	RVA	Sample
LM4050QAEM3-8.2/NOPB	ACTIVE	SOT-23	DBZ	3	1000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 125	RXA	Sample
LM4050QAEM3X10/NOPB	ACTIVE	SOT-23	DBZ	3	3000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 125	RYA	Sample
LM4050QAEM3X2.0/NOPB	ACTIVE	SOT-23	DBZ	3	3000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 125	RSA	Sample
LM4050QAEM3X2.5/NOPB	ACTIVE	SOT-23	DBZ	3	3000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 125	RTA	Sample
LM4050QAEM3X4.1/NOPB	ACTIVE	SOT-23	DBZ	3	3000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 125	RUA	Sample
LM4050QAEM3X5.0/NOPB	ACTIVE	SOT-23	DBZ	3	3000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 125	RVA	Sample
LM4050QAEM3X8.2/NOPB	ACTIVE	SOT-23	DBZ	3	3000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 125	RXA	Sample
LM4050QAIM3-10/NOPB	ACTIVE	SOT-23	DBZ	3	1000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 125	RYA	Sample
LM4050QAIM3-2.0/NOPB	ACTIVE	SOT-23	DBZ	3	1000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 125	RSA	Sample
LM4050QAIM3-2.5/NOPB	ACTIVE	SOT-23	DBZ	3	1000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 125	RTA	Sample
LM4050QAIM3-4.1/NOPB	ACTIVE	SOT-23	DBZ	3	1000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 125	RUA	Sample



Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Sample
LM4050QAIM3-5.0/NOPB	ACTIVE	SOT-23	DBZ	3	1000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 125	RVA	Sample
LM4050QAIM3-8.2/NOPB	ACTIVE	SOT-23	DBZ	3	1000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 125	RXA	Sample
LM4050QAIM3X10/NOPB	ACTIVE	SOT-23	DBZ	3	3000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 125	RYA	Sample
LM4050QAIM3X2.0/NOPB	ACTIVE	SOT-23	DBZ	3	3000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 125	RSA	Sample
LM4050QAIM3X2.5/NOPB	ACTIVE	SOT-23	DBZ	3	3000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 125	RTA	Sample
LM4050QAIM3X4.1/NOPB	ACTIVE	SOT-23	DBZ	3	3000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 125	RUA	Sample
LM4050QAIM3X5.0/NOPB	ACTIVE	SOT-23	DBZ	3	3000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 125	RVA	Sample
LM4050QAIM3X8.2/NOPB	ACTIVE	SOT-23	DBZ	3	3000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 125	RXA	Sample
LM4050QBEM3-10/NOPB	ACTIVE	SOT-23	DBZ	3	1000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 125	RYB	Sample
LM4050QBEM3-2.0/NOPB	ACTIVE	SOT-23	DBZ	3	1000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 125	RSB	Sample
LM4050QBEM3-2.5/NOPB	ACTIVE	SOT-23	DBZ	3	1000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 125	RTB	Sample
LM4050QBEM3-4.1/NOPB	ACTIVE	SOT-23	DBZ	3	1000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 125	RUB	Sample
LM4050QBEM3-5.0/NOPB	ACTIVE	SOT-23	DBZ	3	1000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 125	RVB	Sample
LM4050QBEM3-8.2/NOPB	ACTIVE	SOT-23	DBZ	3	1000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 125	RXB	Sample
LM4050QBEM3X10/NOPB	ACTIVE	SOT-23	DBZ	3	3000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 125	RYB	Sample
LM4050QBEM3X2.0/NOPB	ACTIVE	SOT-23	DBZ	3	3000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 125	RSB	Sample
LM4050QBEM3X2.5/NOPB	ACTIVE	SOT-23	DBZ	3	3000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 125	RTB	Sample
LM4050QBEM3X4.1/NOPB	ACTIVE	SOT-23	DBZ	3	3000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 125	RUB	Sample



Orderable Device	Status (1)	Package Type	Package Drawing	Pins I	Package Qty	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Sample
LM4050QBEM3X5.0/NOPB	ACTIVE	SOT-23	DBZ	3	3000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 125	RVB	Sample
LM4050QBEM3X8.2/NOPB	ACTIVE	SOT-23	DBZ	3	3000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 125	RXB	Sample
LM4050QBIM3-10/NOPB	ACTIVE	SOT-23	DBZ	3	1000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 125	RYB	Sample
LM4050QBIM3-2.0/NOPB	ACTIVE	SOT-23	DBZ	3	1000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 125	RSB	Sample
LM4050QBIM3-2.5/NOPB	ACTIVE	SOT-23	DBZ	3	1000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 125	RTB	Sample
LM4050QBIM3-4.1/NOPB	ACTIVE	SOT-23	DBZ	3	1000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 125	RUB	Sample
LM4050QBIM3-5.0/NOPB	ACTIVE	SOT-23	DBZ	3	1000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 125	RVB	Sample
LM4050QBIM3-8.2/NOPB	ACTIVE	SOT-23	DBZ	3	1000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 125	RXB	Sample
LM4050QBIM3X10/NOPB	ACTIVE	SOT-23	DBZ	3	3000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 125	RYB	Sample
LM4050QBIM3X2.0/NOPB	ACTIVE	SOT-23	DBZ	3	3000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 125	RSB	Sample
LM4050QBIM3X2.5/NOPB	ACTIVE	SOT-23	DBZ	3	3000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 125	RTB	Sample
LM4050QBIM3X4.1/NOPB	ACTIVE	SOT-23	DBZ	3	3000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 125	RUB	Sample
LM4050QBIM3X5.0/NOPB	ACTIVE	SOT-23	DBZ	3	3000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 125	RVB	Sample
LM4050QBIM3X8.2/NOPB	ACTIVE	SOT-23	DBZ	3	3000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 125	RXB	Sample
LM4050QCEM3-10/NOPB	ACTIVE	SOT-23	DBZ	3	1000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 125	RYC	Sample
LM4050QCEM3-2.0/NOPB	ACTIVE	SOT-23	DBZ	3	1000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 125	RSC	Sample
LM4050QCEM3-2.5/NOPB	ACTIVE	SOT-23	DBZ	3	1000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 125	RTC	Sample
LM4050QCEM3-4.1/NOPB	ACTIVE	SOT-23	DBZ	3	1000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 125	RUC	Sample



Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Sample
LM4050QCEM3-5.0/NOPB	ACTIVE	SOT-23	DBZ	3	1000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 125	RVC	Sample
LM4050QCEM3-8.2/NOPB	ACTIVE	SOT-23	DBZ	3	1000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 125	RXC	Sample
LM4050QCEM3X10/NOPB	ACTIVE	SOT-23	DBZ	3	3000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 125	RYC	Sample
LM4050QCEM3X2.0/NOPB	ACTIVE	SOT-23	DBZ	3	3000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 125	RSC	Sample
LM4050QCEM3X2.5/NOPB	ACTIVE	SOT-23	DBZ	3	3000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 125	RTC	Sample
LM4050QCEM3X4.1/NOPB	ACTIVE	SOT-23	DBZ	3	3000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 125	RUC	Sample
LM4050QCEM3X5.0/NOPB	ACTIVE	SOT-23	DBZ	3	3000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 125	RVC	Sample
LM4050QCEM3X8.2/NOPB	ACTIVE	SOT-23	DBZ	3	3000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 125	RXC	Sample
LM4050QCIM3-10/NOPB	ACTIVE	SOT-23	DBZ	3	1000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 125	RYC	Sample
LM4050QCIM3-2.0/NOPB	ACTIVE	SOT-23	DBZ	3	1000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 125	RSC	Sample
LM4050QCIM3-2.5/NOPB	ACTIVE	SOT-23	DBZ	3	1000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 125	RTC	Sample
LM4050QCIM3-4.1/NOPB	ACTIVE	SOT-23	DBZ	3	1000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 125	RUC	Sample
LM4050QCIM3-5.0/NOPB	ACTIVE	SOT-23	DBZ	3	1000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 125	RVC	Sample
LM4050QCIM3-8.2/NOPB	ACTIVE	SOT-23	DBZ	3	1000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 125	RXC	Sample
LM4050QCIM3X10/NOPB	ACTIVE	SOT-23	DBZ	3	3000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 125	RYC	Sample
LM4050QCIM3X2.0/NOPB	ACTIVE	SOT-23	DBZ	3	3000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 125	RSC	Sample
LM4050QCIM3X2.5/NOPB	ACTIVE	SOT-23	DBZ	3	3000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 125	RTC	Sample
LM4050QCIM3X4.1/NOPB	ACTIVE	SOT-23	DBZ	3	3000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 125	RUC	Sample



PACKAGE OPTION ADDENDUM

27-Aug-2015

Orderable Device	Status	Package Type	Package	Pins	-	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking	Samples
	(1)		Drawing		Qty	(2)	(6)	(3)		(4/5)	
LM4050QCIM3X5.0/NOPB	ACTIVE	SOT-23	DBZ	3	3000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 125	RVC	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead/Ball Finish Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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OTHER QUALIFIED VERSIONS OF LM4050-N, LM4050-N-Q1:



PACKAGE OPTION ADDENDUM

27-Aug-2015

www.ti.com

• Automotive: LM4050-N-Q1

NOTE: Qualified Version Definitions:

Catalog - TI's standard catalog product

• Automotive - Q100 devices qualified for high-reliability automotive applications targeting zero defects

www.ti.com 2-Sep-2015

TAPE AND REEL INFORMATION





	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
LM4050AEM3-10/NOPB	SOT-23	DBZ	3	1000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM4050AEM3-2.0/NOPB	SOT-23	DBZ	3	1000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM4050AEM3-2.5	SOT-23	DBZ	3	1000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM4050AEM3-2.5/NOPB	SOT-23	DBZ	3	1000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM4050AEM3-5.0	SOT-23	DBZ	3	1000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM4050AEM3-5.0/NOPB	SOT-23	DBZ	3	1000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM4050AEM3-8.2	SOT-23	DBZ	3	1000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM4050AEM3-8.2/NOPB	SOT-23	DBZ	3	1000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM4050AEM3X-10/NOPB	SOT-23	DBZ	3	3000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM4050AEM3X-2.5/NOPB	SOT-23	DBZ	3	3000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM4050AEM3X-5.0/NOPB	SOT-23	DBZ	3	3000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM4050AIM3-10	SOT-23	DBZ	3	1000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM4050AIM3-10/NOPB	SOT-23	DBZ	3	1000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM4050AIM3-2.5	SOT-23	DBZ	3	1000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM4050AIM3-2.5/NOPB	SOT-23	DBZ	3	1000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM4050AIM3-4.1	SOT-23	DBZ	3	1000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM4050AIM3-4.1/NOPB	SOT-23	DBZ	3	1000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM4050AIM3-5.0	SOT-23	DBZ	3	1000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3



Device		Package	Pins	SPQ	Reel Diameter	Reel Width	A0	B0	K0	P1	W (mm)	Pin1
	Туре	Drawing			(mm)	W1 (mm)	(mm)	(mm)	(mm)	(mm)	(mm)	Quadrant
LM4050AIM3-5.0/NOPB	SOT-23	DBZ	3	1000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM4050AIM3X-2.5/NOPB	SOT-23	DBZ	3	3000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM4050AIM3X-4.1/NOPB	SOT-23	DBZ	3	3000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM4050AIM3X-5.0	SOT-23	DBZ	3	3000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM4050AIM3X-5.0/NOPB	SOT-23	DBZ	3	3000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM4050BEM3-10/NOPB	SOT-23	DBZ	3	1000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM4050BEM3-2.5	SOT-23	DBZ	3	1000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM4050BEM3-2.5/NOPB	SOT-23	DBZ	3	1000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM4050BEM3-4.1/NOPB	SOT-23	DBZ	3	1000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM4050BEM3-5.0	SOT-23	DBZ	3	1000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM4050BEM3-5.0/NOPB	SOT-23	DBZ	3	1000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM4050BEM3-8.2/NOPB	SOT-23	DBZ	3	1000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM4050BEM3X-10/NOPB	SOT-23	DBZ	3	3000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM4050BEM3X-2.5/NOPB	SOT-23	DBZ	3	3000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM4050BEM3X-5.0/NOPB		DBZ	3	3000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM4050BIM3-10/NOPB	SOT-23	DBZ	3	1000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM4050BIM3-2.5	SOT-23	DBZ	3	1000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM4050BIM3-2.5/NOPB	SOT-23	DBZ	3	1000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM4050BIM3-4.1/NOPB	SOT-23	DBZ	3	1000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM4050BIM3-5.0	SOT-23	DBZ	3	1000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM4050BIM3-5.0/NOPB	SOT-23	DBZ	3	1000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM4050BIM3X-2.0/NOPB	SOT-23	DBZ	3	3000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM4050BIM3X-2.5/NOPB	SOT-23	DBZ	3	3000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM4050BIM3X-4.1/NOPB	SOT-23	DBZ	3	3000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM4050BIM3X-5.0/NOPB	SOT-23	DBZ	3	3000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM4050CEM3-10/NOPB	SOT-23	DBZ	3	1000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM4050CEM3-2.5	SOT-23	DBZ	3	1000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM4050CEM3-2.5/NOPB	SOT-23	DBZ	3	1000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM4050CEM3-5.0	SOT-23	DBZ	3	1000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM4050CEM3-5.0/NOPB	SOT-23	DBZ	3	1000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM4050CEM3X-2.5/NOPB	SOT-23	DBZ	3	3000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM4050CEM3X-5.0/NOPB	SOT-23	DBZ	3	3000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM4050CIM3-10/NOPB	SOT-23	DBZ	3	1000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM4050CIM3-2.5	SOT-23	DBZ	3	1000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM4050CIM3-2.5/NOPB	SOT-23	DBZ	3	1000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM4050CIM3-4.1	SOT-23	DBZ	3	1000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM4050CIM3-4.1/NOPB	SOT-23	DBZ	3	1000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM4050CIM3-5.0	SOT-23	DBZ	3	1000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM4050CIM3-5.0/NOPB	SOT-23	DBZ	3	1000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM4050CIM3X-2.0/NOPB	SOT-23	DBZ	3	3000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM4050CIM3X-2.5/NOPB		DBZ	3	3000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM4050CIM3X-4.1/NOPB		DBZ	3	3000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM4050CIM3X-5.0/NOPB		DBZ	3	3000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3



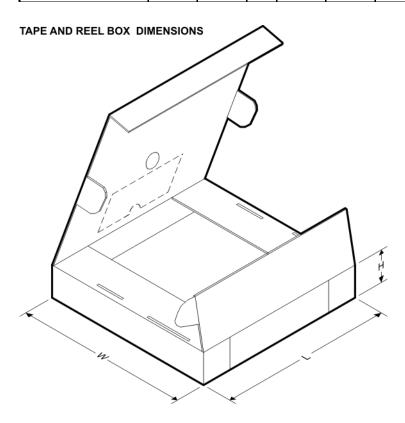
Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
LM4050QAEM3-10/NOPB	SOT-23	DBZ	3	1000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM4050QAEM3-2.0/NOP B	SOT-23	DBZ	3	1000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM4050QAEM3-2.5/NOP B	SOT-23	DBZ	3	1000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM4050QAEM3-4.1/NOP B	SOT-23	DBZ	3	1000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM4050QAEM3-5.0/NOP B	SOT-23	DBZ	3	1000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM4050QAEM3-8.2/NOP B	SOT-23	DBZ	3	1000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM4050QAEM3X10/NOP B	SOT-23	DBZ	3	3000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
_M4050QAEM3X2.0/NOP B	SOT-23	DBZ	3	3000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
_M4050QAEM3X2.5/NOP B	SOT-23	DBZ	3	3000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
_M4050QAEM3X4.1/NOP B	SOT-23	DBZ	3	3000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
_M4050QAEM3X5.0/NOP B	SOT-23	DBZ	3	3000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
M4050QAEM3X8.2/NOP B	SOT-23	DBZ	3	3000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM4050QAIM3-10/NOPB	SOT-23	DBZ	3	1000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM4050QAIM3-2.0/NOPB	SOT-23	DBZ	3	1000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM4050QAIM3-2.5/NOPB	SOT-23	DBZ	3	1000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM4050QAIM3-4.1/NOPB	SOT-23	DBZ	3	1000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM4050QAIM3-5.0/NOPB	SOT-23	DBZ	3	1000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM4050QAIM3-8.2/NOPB	SOT-23	DBZ	3	1000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM4050QAIM3X10/NOPB	SOT-23	DBZ	3	3000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM4050QAIM3X2.0/NOPB	SOT-23	DBZ	3	3000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM4050QAIM3X2.5/NOPB	SOT-23	DBZ	3	3000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM4050QAIM3X4.1/NOPB	SOT-23	DBZ	3	3000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM4050QAIM3X5.0/NOPB	SOT-23	DBZ	3	3000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM4050QAIM3X8.2/NOPB	SOT-23	DBZ	3	3000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM4050QBEM3-10/NOPB	SOT-23	DBZ	3	1000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM4050QBEM3-2.0/NOP B	SOT-23	DBZ	3	1000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM4050QBEM3-2.5/NOP B	SOT-23	DBZ	3	1000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM4050QBEM3-4.1/NOP B	SOT-23	DBZ	3	1000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM4050QBEM3-5.0/NOP B	SOT-23	DBZ	3	1000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM4050QBEM3-8.2/NOP B	SOT-23	DBZ	3	1000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM4050QBEM3X10/NOP B	SOT-23	DBZ	3	3000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3



Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
_M4050QBEM3X2.0/NOP B	SOT-23	DBZ	3	3000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
_M4050QBEM3X2.5/NOP B	SOT-23	DBZ	3	3000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
M4050QBEM3X4.1/NOP B	SOT-23	DBZ	3	3000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM4050QBEM3X5.0/NOP B	SOT-23	DBZ	3	3000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM4050QBEM3X8.2/NOP B	SOT-23	DBZ	3	3000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM4050QBIM3-10/NOPB	SOT-23	DBZ	3	1000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM4050QBIM3-2.0/NOPB	SOT-23	DBZ	3	1000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM4050QBIM3-2.5/NOPB	SOT-23	DBZ	3	1000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM4050QBIM3-4.1/NOPB	SOT-23	DBZ	3	1000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM4050QBIM3-5.0/NOPB	SOT-23	DBZ	3	1000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM4050QBIM3-8.2/NOPB	SOT-23	DBZ	3	1000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM4050QBIM3X10/NOPB	SOT-23	DBZ	3	3000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM4050QBIM3X2.0/NOPB	SOT-23	DBZ	3	3000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM4050QBIM3X2.5/NOPB	SOT-23	DBZ	3	3000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM4050QBIM3X4.1/NOPB	SOT-23	DBZ	3	3000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM4050QBIM3X5.0/NOPB	SOT-23	DBZ	3	3000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM4050QBIM3X8.2/NOPB	SOT-23	DBZ	3	3000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM4050QCEM3-10/NOPB	SOT-23	DBZ	3	1000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM4050QCEM3-2.0/NOP B	SOT-23	DBZ	3	1000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM4050QCEM3-2.5/NOP B	SOT-23	DBZ	3	1000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM4050QCEM3-4.1/NOP B	SOT-23	DBZ	3	1000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM4050QCEM3-5.0/NOP B	SOT-23	DBZ	3	1000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM4050QCEM3-8.2/NOP B	SOT-23	DBZ	3	1000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM4050QCEM3X10/NOP B	SOT-23	DBZ	3	3000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
_M4050QCEM3X2.0/NOP B	SOT-23	DBZ	3	3000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
_M4050QCEM3X2.5/NOP B	SOT-23	DBZ	3	3000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
_M4050QCEM3X4.1/NOP B	SOT-23	DBZ	3	3000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
_M4050QCEM3X5.0/NOP B	SOT-23	DBZ	3	3000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
M4050QCEM3X8.2/NOP B	SOT-23	DBZ	3	3000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM4050QCIM3-10/NOPB	SOT-23	DBZ	3	1000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM4050QCIM3-2.0/NOPB	SOT-23	DBZ	3	1000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM4050QCIM3-2.5/NOPB	SOT-23	DBZ	3	1000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3

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Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
LM4050QCIM3-4.1/NOPB	SOT-23	DBZ	3	1000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM4050QCIM3-5.0/NOPB	SOT-23	DBZ	3	1000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM4050QCIM3-8.2/NOPB	SOT-23	DBZ	3	1000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM4050QCIM3X10/NOPB	SOT-23	DBZ	3	3000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM4050QCIM3X2.0/NOP B	SOT-23	DBZ	3	3000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM4050QCIM3X2.5/NOP B	SOT-23	DBZ	3	3000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM4050QCIM3X4.1/NOP B	SOT-23	DBZ	3	3000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM4050QCIM3X5.0/NOP B	SOT-23	DBZ	3	3000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
LM4050AEM3-10/NOPB	SOT-23	DBZ	3	1000	210.0	185.0	35.0
LM4050AEM3-2.0/NOPB	SOT-23	DBZ	3	1000	210.0	185.0	35.0
LM4050AEM3-2.5	SOT-23	DBZ	3	1000	210.0	185.0	35.0
LM4050AEM3-2.5/NOPB	SOT-23	DBZ	3	1000	210.0	185.0	35.0
LM4050AEM3-5.0	SOT-23	DBZ	3	1000	210.0	185.0	35.0
LM4050AEM3-5.0/NOPB	SOT-23	DBZ	3	1000	210.0	185.0	35.0



Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
LM4050AEM3-8.2	SOT-23	DBZ	3	1000	210.0	185.0	35.0
LM4050AEM3-8.2/NOPB	SOT-23	DBZ	3	1000	210.0	185.0	35.0
LM4050AEM3X-10/NOPB	SOT-23	DBZ	3	3000	210.0	185.0	35.0
LM4050AEM3X-2.5/NOPB	SOT-23	DBZ	3	3000	210.0	185.0	35.0
LM4050AEM3X-5.0/NOPB	SOT-23	DBZ	3	3000	210.0	185.0	35.0
LM4050AIM3-10	SOT-23	DBZ	3	1000	210.0	185.0	35.0
LM4050AIM3-10/NOPB	SOT-23	DBZ	3	1000	210.0	185.0	35.0
LM4050AIM3-2.5	SOT-23	DBZ	3	1000	210.0	185.0	35.0
LM4050AIM3-2.5/NOPB	SOT-23	DBZ	3	1000	210.0	185.0	35.0
LM4050AIM3-4.1	SOT-23	DBZ	3	1000	210.0	185.0	35.0
LM4050AIM3-4.1/NOPB	SOT-23	DBZ	3	1000	210.0	185.0	35.0
LM4050AIM3-5.0	SOT-23	DBZ	3	1000	210.0	185.0	35.0
LM4050AIM3-5.0/NOPB	SOT-23	DBZ	3	1000	210.0	185.0	35.0
LM4050AIM3X-2.5/NOPB	SOT-23	DBZ	3	3000	210.0	185.0	35.0
LM4050AIM3X-4.1/NOPB	SOT-23	DBZ	3	3000	210.0	185.0	35.0
LM4050AIM3X-5.0	SOT-23	DBZ	3	3000	210.0	185.0	35.0
LM4050AIM3X-5.0/NOPB	SOT-23	DBZ	3	3000	210.0	185.0	35.0
LM4050BEM3-10/NOPB	SOT-23	DBZ	3	1000	210.0	185.0	35.0
LM4050BEM3-2.5	SOT-23	DBZ	3	1000	210.0	185.0	35.0
LM4050BEM3-2.5/NOPB	SOT-23	DBZ	3	1000	210.0	185.0	35.0
LM4050BEM3-4.1/NOPB	SOT-23	DBZ	3	1000	210.0	185.0	35.0
LM4050BEM3-5.0	SOT-23	DBZ	3	1000	210.0	185.0	35.0
LM4050BEM3-5.0/NOPB	SOT-23	DBZ	3	1000	210.0	185.0	35.0
LM4050BEM3-8.2/NOPB	SOT-23	DBZ	3	1000	210.0	185.0	35.0
LM4050BEM3X-10/NOPB	SOT-23	DBZ	3	3000	210.0	185.0	35.0
LM4050BEM3X-2.5/NOPB	SOT-23	DBZ	3	3000	210.0	185.0	35.0
LM4050BEM3X-5.0/NOPB	SOT-23	DBZ	3	3000	210.0	185.0	35.0
LM4050BIM3-10/NOPB	SOT-23	DBZ	3	1000	210.0	185.0	35.0
LM4050BIM3-2.5	SOT-23	DBZ	3	1000	210.0	185.0	35.0
LM4050BIM3-2.5/NOPB	SOT-23	DBZ	3	1000	210.0	185.0	35.0
LM4050BIM3-4.1/NOPB	SOT-23	DBZ	3	1000	210.0	185.0	35.0
LM4050BIM3-5.0	SOT-23	DBZ	3	1000	210.0	185.0	35.0
LM4050BIM3-5.0/NOPB	SOT-23	DBZ	3	1000	210.0	185.0	35.0
LM4050BIM3X-2.0/NOPB	SOT-23	DBZ	3	3000	210.0	185.0	35.0
LM4050BIM3X-2.5/NOPB	SOT-23	DBZ	3	3000	210.0	185.0	35.0
LM4050BIM3X-4.1/NOPB	SOT-23	DBZ	3	3000	210.0	185.0	35.0
LM4050BIM3X-5.0/NOPB	SOT-23	DBZ	3	3000	210.0	185.0	35.0
LM4050CEM3-10/NOPB	SOT-23	DBZ	3	1000	210.0	185.0	35.0
LM4050CEM3-2.5	SOT-23	DBZ	3	1000	210.0	185.0	35.0
LM4050CEM3-2.5/NOPB	SOT-23	DBZ	3	1000	210.0	185.0	35.0
LM4050CEM3-5.0	SOT-23	DBZ	3	1000	210.0	185.0	35.0
LM4050CEM3-5.0/NOPB	SOT-23	DBZ	3	1000	210.0	185.0	35.0
LM4050CEM3X-2.5/NOPB	SOT-23	DBZ	3	3000	210.0	185.0	35.0
LM4050CEM3X-5.0/NOPB	SOT-23	DBZ	3	3000	210.0	185.0	35.0



Device	Bookaga Tyrna	Package Drawing	Pins	SPQ	Longth (mm)	Width (mm)	Hoight (mm)
	Package Type				Length (mm)	. ,	Height (mm)
LM4050CIM3-10/NOPB	SOT-23	DBZ	3	1000	210.0	185.0	35.0
LM4050CIM3-2.5	SOT-23	DBZ	3	1000	210.0	185.0	35.0
LM4050CIM3-2.5/NOPB	SOT-23	DBZ	3	1000	210.0	185.0	35.0
LM4050CIM3-4.1	SOT-23	DBZ	3	1000	210.0	185.0	35.0
LM4050CIM3-4.1/NOPB	SOT-23	DBZ	3	1000	210.0	185.0	35.0
LM4050CIM3-5.0	SOT-23	DBZ	3	1000	210.0	185.0	35.0
LM4050CIM3-5.0/NOPB	SOT-23	DBZ	3	1000	210.0	185.0	35.0
LM4050CIM3X-2.0/NOPB	SOT-23	DBZ	3	3000	210.0	185.0	35.0
LM4050CIM3X-2.5/NOPB	SOT-23	DBZ	3	3000	210.0	185.0	35.0
LM4050CIM3X-4.1/NOPB	SOT-23	DBZ	3	3000	210.0	185.0	35.0
LM4050CIM3X-5.0/NOPB	SOT-23	DBZ	3	3000	210.0	185.0	35.0
LM4050QAEM3-10/NOPB	SOT-23	DBZ	3	1000	210.0	185.0	35.0
LM4050QAEM3-2.0/NOPB	SOT-23	DBZ	3	1000	210.0	185.0	35.0
LM4050QAEM3-2.5/NOPB	SOT-23	DBZ	3	1000	210.0	185.0	35.0
LM4050QAEM3-4.1/NOPB	SOT-23	DBZ	3	1000	210.0	185.0	35.0
LM4050QAEM3-5.0/NOPB	SOT-23	DBZ	3	1000	210.0	185.0	35.0
LM4050QAEM3-8.2/NOPB	SOT-23	DBZ	3	1000	210.0	185.0	35.0
LM4050QAEM3X10/NOPB	SOT-23	DBZ	3	3000	210.0	185.0	35.0
LM4050QAEM3X2.0/NOP B	SOT-23	DBZ	3	3000	210.0	185.0	35.0
LM4050QAEM3X2.5/NOP B	SOT-23	DBZ	3	3000	210.0	185.0	35.0
LM4050QAEM3X4.1/NOP B	SOT-23	DBZ	3	3000	210.0	185.0	35.0
LM4050QAEM3X5.0/NOP B	SOT-23	DBZ	3	3000	210.0	185.0	35.0
LM4050QAEM3X8.2/NOP B	SOT-23	DBZ	3	3000	210.0	185.0	35.0
LM4050QAIM3-10/NOPB	SOT-23	DBZ	3	1000	210.0	185.0	35.0
LM4050QAIM3-2.0/NOPB	SOT-23	DBZ	3	1000	210.0	185.0	35.0
LM4050QAIM3-2.5/NOPB	SOT-23	DBZ	3	1000	210.0	185.0	35.0
LM4050QAIM3-4.1/NOPB	SOT-23	DBZ	3	1000	210.0	185.0	35.0
LM4050QAIM3-5.0/NOPB	SOT-23	DBZ	3	1000	210.0	185.0	35.0
LM4050QAIM3-8.2/NOPB	SOT-23	DBZ	3	1000	210.0	185.0	35.0
LM4050QAIM3X10/NOPB	SOT-23	DBZ	3	3000	210.0	185.0	35.0
LM4050QAIM3X2.0/NOPB	SOT-23	DBZ	3	3000	210.0	185.0	35.0
LM4050QAIM3X2.5/NOPB	SOT-23	DBZ	3	3000	210.0	185.0	35.0
LM4050QAIM3X4.1/NOPB	SOT-23	DBZ	3	3000	210.0	185.0	35.0
LM4050QAIM3X5.0/NOPB	SOT-23	DBZ	3	3000	210.0	185.0	35.0
LM4050QAIM3X8.2/NOPB	SOT-23	DBZ	3	3000	210.0	185.0	35.0
LM4050QBEM3-10/NOPB	SOT-23	DBZ	3	1000	210.0	185.0	35.0
LM4050QBEM3-2.0/NOPB	SOT-23	DBZ	3	1000	210.0	185.0	35.0
LM4050QBEM3-2.5/NOPB	SOT-23	DBZ	3	1000	210.0	185.0	35.0
LM4050QBEM3-4.1/NOPB	SOT-23	DBZ	3	1000	210.0	185.0	35.0
LM4050QBEM3-5.0/NOPB	SOT-23	DBZ	3	1000	210.0	185.0	35.0



Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
LM4050QBEM3-8.2/NOPB	SOT-23	DBZ	3	1000	210.0	185.0	35.0
LM4050QBEM3X10/NOPB	SOT-23	DBZ	3	3000	210.0	185.0	35.0
LM4050QBEM3X2.0/NOP B	SOT-23	DBZ	3	3000	210.0	185.0	35.0
LM4050QBEM3X2.5/NOP B	SOT-23	DBZ	3	3000	210.0	185.0	35.0
LM4050QBEM3X4.1/NOP B	SOT-23	DBZ	3	3000	210.0	185.0	35.0
LM4050QBEM3X5.0/NOP B	SOT-23	DBZ	3	3000	210.0	185.0	35.0
LM4050QBEM3X8.2/NOP B	SOT-23	DBZ	3	3000	210.0	185.0	35.0
LM4050QBIM3-10/NOPB	SOT-23	DBZ	3	1000	210.0	185.0	35.0
LM4050QBIM3-2.0/NOPB	SOT-23	DBZ	3	1000	210.0	185.0	35.0
LM4050QBIM3-2.5/NOPB	SOT-23	DBZ	3	1000	210.0	185.0	35.0
LM4050QBIM3-4.1/NOPB	SOT-23	DBZ	3	1000	210.0	185.0	35.0
LM4050QBIM3-5.0/NOPB	SOT-23	DBZ	3	1000	210.0	185.0	35.0
LM4050QBIM3-8.2/NOPB	SOT-23	DBZ	3	1000	210.0	185.0	35.0
LM4050QBIM3X10/NOPB	SOT-23	DBZ	3	3000	210.0	185.0	35.0
LM4050QBIM3X2.0/NOPB	SOT-23	DBZ	3	3000	210.0	185.0	35.0
LM4050QBIM3X2.5/NOPB	SOT-23	DBZ	3	3000	210.0	185.0	35.0
LM4050QBIM3X4.1/NOPB	SOT-23	DBZ	3	3000	210.0	185.0	35.0
LM4050QBIM3X5.0/NOPB	SOT-23	DBZ	3	3000	210.0	185.0	35.0
LM4050QBIM3X8.2/NOPB	SOT-23	DBZ	3	3000	210.0	185.0	35.0
LM4050QCEM3-10/NOPB	SOT-23	DBZ	3	1000	210.0	185.0	35.0
LM4050QCEM3-2.0/NOPB	SOT-23	DBZ	3	1000	210.0	185.0	35.0
LM4050QCEM3-2.5/NOPB	SOT-23	DBZ	3	1000	210.0	185.0	35.0
LM4050QCEM3-4.1/NOPB	SOT-23	DBZ	3	1000	210.0	185.0	35.0
LM4050QCEM3-5.0/NOPB	SOT-23	DBZ	3	1000	210.0	185.0	35.0
LM4050QCEM3-8.2/NOPB	SOT-23	DBZ	3	1000	210.0	185.0	35.0
LM4050QCEM3X10/NOPB	SOT-23	DBZ	3	3000	210.0	185.0	35.0
LM4050QCEM3X2.0/NOP B	SOT-23	DBZ	3	3000	210.0	185.0	35.0
LM4050QCEM3X2.5/NOP B	SOT-23	DBZ	3	3000	210.0	185.0	35.0
LM4050QCEM3X4.1/NOP B	SOT-23	DBZ	3	3000	210.0	185.0	35.0
LM4050QCEM3X5.0/NOP B	SOT-23	DBZ	3	3000	210.0	185.0	35.0
LM4050QCEM3X8.2/NOP B	SOT-23	DBZ	3	3000	210.0	185.0	35.0
LM4050QCIM3-10/NOPB	SOT-23	DBZ	3	1000	210.0	185.0	35.0
LM4050QCIM3-2.0/NOPB	SOT-23	DBZ	3	1000	210.0	185.0	35.0
LM4050QCIM3-2.5/NOPB	SOT-23	DBZ	3	1000	210.0	185.0	35.0
LM4050QCIM3-4.1/NOPB	SOT-23	DBZ	3	1000	210.0	185.0	35.0
LM4050QCIM3-5.0/NOPB	SOT-23	DBZ	3	1000	210.0	185.0	35.0
LM4050QCIM3-8.2/NOPB	SOT-23	DBZ	3	1000	210.0	185.0	35.0



Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
LM4050QCIM3X10/NOPB	SOT-23	DBZ	3	3000	210.0	185.0	35.0
LM4050QCIM3X2.0/NOPB	SOT-23	DBZ	3	3000	210.0	185.0	35.0
LM4050QCIM3X2.5/NOPB	SOT-23	DBZ	3	3000	210.0	185.0	35.0
LM4050QCIM3X4.1/NOPB	SOT-23	DBZ	3	3000	210.0	185.0	35.0
LM4050QCIM3X5.0/NOPB	SOT-23	DBZ	3	3000	210.0	185.0	35.0

DBZ (R-PDSO-G3)

PLASTIC SMALL-OUTLINE



NOTES: A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.

- B. This drawing is subject to change without notice.
- C. Lead dimensions are inclusive of plating.
- D. Body dimensions are exclusive of mold flash and protrusion. Mold flash and protrusion not to exceed 0.25 per side.
- Falls within JEDEC TO-236 variation AB, except minimum foot length.



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